

Poster ID	ID		Title
FRI-P01	11	Student	Al-Doped CeO₂ as High-Performance Abrasives for Glass Chemical Mechanical Polishing Haoyuan Wu, Qinghua Xu, Guosheng Yang, Yan Zhao, Xiping Qu, Hang Wei, Simin Li, Fan Zhang, Hui Shen* Inner Mongolia University
FRI-P02	12	Student	Computational Fluid Dynamics (CFD) Studies of CMP Pad Considering Surface Roughness shin il Oh, Taesung Kim* Sungkyunkwan University
FRI-P03	18		Challenges of Barrier CMP Slurry for Hybrid Bonding Interconnect Shogo Onishi*, Lexi Carlson, Glenn Whitener, Hisashi Takeda, Kazumi Sugai FUJIMI Incorporated
FRI-P04	26	student	Slurry Flow Redistribution in Cu Bulk CMP for Cost and Process Efficiency Optimization Yoojin Son, Taesung Kim*
FRI-P05	123	Student	CMP Optimization for Electroplated Nanotwinned and Nanocrystalline Copper Films: Enabling Cu-Cu Direct Bonding in 3D Advanced Packaging Yuanxing Duan, Shichen Xie, Ziting Ye, Yifan Yao, Lulin Xie, Xingchao Mao, Fuxin Du, Yingxia Liu* City University of Hong Kong
FRI-P06	127	Student	The Stability Evaluation of Highly Dispersed Ceria Slurry Using Non-Ion Dispersant for CMP Process Jaeyeong Cho, Sohee Hwang, Jinsu Kang, Woonjung Kim* Hannam University
FRI-P07	52		Innovative Synergies in Slurry and PCMP for Wafer Back-Side TSV CMP Achieving Higher Throughput and Improved Surface Quality Allison Hsu, Jacky Cheng* Qnity™, DuPont Electronics
FRI-P08	132	Student	Characteristic Analysis of Ceria Nanoparticle Slurry for CMP Process Using Liquid Phase Method Suyeon Seo, Sohee Hwang, Jaeyoung Cho, Chaeyeon Kim, Woonjung Kim* Hannam University
FRI-P09	60		Innovative Approach for Surface Defect Reduction Through CMP Mechanical Effect Modulation Zhengqiu Sun*, Wern Jun Mak Micron SemiAsiaOP Pte Ltd.
FRI-P10	134	Student	The Preparation and Characterization of Ceria Nanoparticles Using Reducing Agent at Low Temperature Atmosphere Chaeyeon Kim, Taekyum Kim, Sohee Hwang, Tao Lyu, Woonjung Kim* Hannam University
FRI-P11	66		Removal Rate Estimation on Multi Buffing Slurry System via Machine Learning Bohyeok Choi, Myunggoo Lee, Chanyeon Park, Inseol Hwang, Jaedong Lee* KCTech
FRI-P12	68		Effect of Controlling Cu Oxidation State in Cu-CMP Toshiya KON*, Megumi Uno, Chikako Takatoh Chemical Solution Promoting Section Strategic Technologies Promoting Department Technologies & Intellectual Property Division
FRI-P13	79	Student	Unveiling the Inhibition Mechanism of Cu Corrosion Through Structural Isomerism Dongwon Kim, donggeun Park, ilhwa Hong, ganghyeok Kim, kangchun Lee* Kwangwoon University
FRI-P14	80	Student	PS@CeO₂@PDA Abrasives for High-Planarization and Damage-Free Chemical Mechanical Polishing Xiaohai He, Bo Gao, Wei Yuan, Xiping Qu, Hui Shen, Fan Zhang*, Simin Li Inner Mongolia University
FRI-P15	81		Microfluidic Experimental Characterization and Simulation of Nanoparticle Aggregate Formation and Restructuration in the High Shear Flows Typical of Chemical Mechanical Polishing Process Guillemette Corrieu, Patrice Bacchin*, Yannick Hallez, Mallorie Tourbin University of Toulouse - LGC
FRI-P16	155	Student	Development and Application of Novel Highly Dispersible and Highly Active Ceria Polishing Slurries Yanran Hou, Zihan Chen, Wei Yuan, Fan Zhang* Fudan University
FRI-P17	90		Slurry Injection Schemes Based on Flow Field Distribution During Chemical Mechanical Polishing Process Hui Ci, Lifei Zhang*, Nanhao Zhao, Dewen Zhao, Xinchun Lu Hwatsing Technology Co. Ltd.
FRI-P18	156	Student	Novel Dendritic Mesoporous Ceria Abrasives for High-Efficiency Chemical Mechanical Polishing Jinhua Liu, Linlin Zeng, Xiping Qu, Wei Yuan*, Fan Zhang Fudan University
FRI-P19	99		Next Generation of Colloidal Ceria Reka Toth*, Manabu Yuasa, Eisaku Suda, Takao Sekimoto, Arihisa Matsumoto Solvay
FRI-P20	157	Student	Ultra-Small Mesoporous Ceria via One-Step Self-Assembly for Precision CMP of Silica Junyu Cao, Wei Yuan*, Fan Zhang Fudan University
FRI-P21	104		Closed-Loop Optimization of Reactive Force Field Parameters for Cobalt Chemical Mechanical Polishing Process Yating Huang, Zhengmiao Fu, Lifei Zhang*, Jialei Zhang Beijing Technology and Business University
FRI-P22	105		Effect of TAZ as Corrosion Inhibitor for Co and Cu in Chemical Mechanical Polishing (CMP): Insights from Electrochemistry and Triboelectrochemistry Jie Cheng*, Jiahui Ma China University of Mining & Technology
FRI-P23	107	Student	Development of Highly Stable Ceria Abrasive for Effective CMP (Chemical Mechanical Polishing) Process Using Solid State and Liquid Phase Method Sohee Hwang, Woonjung Kim* Hannam University
FRI-P24	113		Influence of Polishing Pad Groove Structure on Polishing Performance During Chemical Mechanical Polishing Process Lifei Zhang*, Nanhao Zhao Hwatsing Technology Co. Ltd.
FRI-P25	116		Design and Evaluation of Novel Colloidal Silica for Superior Removal Rate Yoshiki Michiwaki*, Shunsuke Tanaka, Shun Arai, Shuta Ozawa Fuso Chemical Co.Ltd.
FRI-P26	133	Student	Study on Stability Test of Ceria Slurry Using Synthesized Ceria Nanoparticle via Liquid Phase Method for Chemical Mechanical Polishing (CMP) Performance Won Jeongyeon, Sohee Hwang, Tao Lyu, Woonjung Kim* Hannam University
FRI-P27	136	Student	Effect of KIO₃ on Chemical Mechanical Polishing of Cu/Ni Heterogeneous Microstructures for MEMS Yongshun Zhang, Xin Li, Liang Jiang*, Linmao Qian Southwest Jiaotong University
FRI-P28	142		Study on Planarization of Heterogeneous Materials in Ultraviolet Energy Field-Assisted Chemical Mechanical Polishing Jialei Zhang, Lifei zhang*, Dewen Zhao, Xinchun Lu Tsinghua University
FRI-P29	145		Adaptive Slurry Design Based on an Environmentally Friendly Multi-Functional Additive: Methods and Mechanisms for Atomic-Level Simultaneous Removal of Cobalt Heterostructures Zixin Gao, Lifei zhang* Hwatsing Technology Co. Ltd.
FRI-P30	167	Student	Study on the Dispersion Stability and Chemical Mechanical Polishing Performance of Ceria Nanoparticles at Low Thermal Process Tao Lyu, Sohee Hwang, Sooyeon Choi, Songhui Kim, Woonjung Kim* Hannam University
FRI-P31	148		Analytical Investigation of Retainer Groove Effect on Contact Pressure Distribution Near Wafer Edge in CMP Yohei Hashimoto*, Kansuke Kameyama, Rikuto Endo, Hozumi Yasuda, Norikazu Suzuki Kanazawa University

FRI-P32	169	Student	A New Synthetic Approach For High Surface Area Mesoporous Ceria Core-Shell Composite Abrasive Linlin Zeng, Jinhua Liu, Xiping Qu, Wei Yuan, Fan Zhang* Fudan University
FRI-P33	176	Student	Physical Limitations Due to Wear of Polymer Materials in Gimbal Head Jeewoon choi, Taesung Kim* Sungkyunkwan university
FRI-P34	177		Effect of Sub Pad Properties on Pressure Modulation on Copper Edge Removal in CMP Simone Rizzardini, Valentin Callier, Antonio Del Galdo* STMicroelectronics
FRI-P35	182	Student	Eco-Friendly Organic Antimicrobials for Microbial Control and Agent Replacement in Copper CMP Slurries Gyuyoung Lee, Jaewon Lee, Seunghwan Lee, Taesung Kim* Sungkyunkwan University
FRI-P36	184		Enhancing PECVD aSiC CMP Performance Through Slurry Selection and Pad Surface Texturing Julian Sturm*, Cédric Perrot, Cécile Candegabe, Amélie Lambert, Jean-Pierre Nieto, Frederic Noel, Catherine Euvrard CEA LETI
FRI-P37	189		Experimental and Mechanistic Analysis of Organic Bases for Enhancing Silica CMP Efficiency Zhenyu Wu, Kong Hui, Weili Liu*, Zhitang Song Shanghai Institute of Microsystem and Information Technology
FRI-P38	201	Student	Wear-Tolerant Asperity Design of Micro-Structured Pads for Time-Independent Material Removal Rate Seounghee Yun, Hyun Jun Ryu, Sanha Kim* Korea Advanced Institute of Science and Technology